



MMIC BALUN

# RF Transformer Die

## MTX2-133-D+

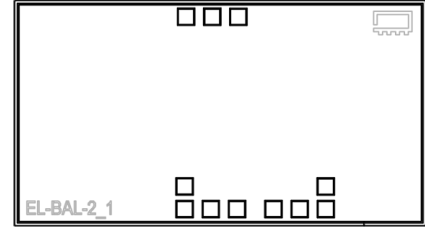
50Ω 1500 to 13000 MHz

### THE BIG DEAL

- Wideband, 1500 to 13000 MHz
- Low insertion loss, 1.9 dB typ. (above theoretical) at 7000 MHz
- Excellent Common Mode Rejection, 34 dB typ.

### APPLICATIONS

- Cellular Infrastructure
- Instrumentation
- RADAR
- Satcom
- Electronic Warfare
- Mixers & Modulators



**+RoHS Compliant**  
 The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

SEE ORDERING INFORMATION ON THE LAST PAGE

### PRODUCT OVERVIEW

Mini-Circuits MTX2-133-D+ is a wideband MMIC balun transformer die with an impedance ratio of 1:2 applicable for a wide range of applications from 1500 to 13000 MHz. Fabricated using GaAs HBT process technology, this model provides outstanding repeatability with low insertion loss, low amplitude unbalance, low phase unbalance, and excellent common mode rejection.

### KEY FEATURES

Feature	Advantages
Wideband, 1500 to 13000 MHz	MTX2-133-D+ supports a broad variety of applications including instrumentation, WLAN, WiMAX, WiBRO, ISM, radar and more.
Low insertion loss • 1.9 dB typ. (above theoretical) at 7000 MHz	Enables excellent signal power transmission from input to output.
Low unbalance • 0.3 dB typ. amplitude unbalance • 1.2° typ. phase unbalance	Low unbalance can improve a system's electromagnetic compatibility by rejecting unwanted common-mode noise.
Excellent Common Mode Rejection • 34 dB typ.	Enables rejection of undesired signals
Unpackaged Die	Enables the user to integrate the balun directly into hybrids.

REV. OR  
 ECO-010992  
 MTX2-133-D+  
 MCLNY  
 211207



**ELECTRICAL SPECIFICATIONS<sup>1</sup> AT 25°C, 50Ω, UNLESS OTHERWISE NOTED.**

Parameter	Frequency (MHz)	Min.	Typ.	Max.	Unit
Impedance Ratio (secondary / primary)			2		
Frequency Range		1500		13000	MHz
Insertion Loss (Above 3 dB Theoretical)	1500-3000		2.3		dB
	3000-10000		1.9		
	10000-13000		2.9		
Amplitude Unbalance	1500-3000		0.6		dB
	3000-10000		0.2		
	10000-13000		0.4		
Phase Unbalance <sup>2</sup>	1500-3000		3.0		Degree
	3000-10000		0.8		
	10000-13000		1.2		
Common Mode Rejection Ratio	1500-3000		28		dB
	3000-10000		36		
	10000-13000		33		
Input Return Loss	1500-3000		11		dB
	3000-10000		14		
	10000-13000		17		

1. Measured on X-Microwave Die Characterization test board.

2. Relative to 180°

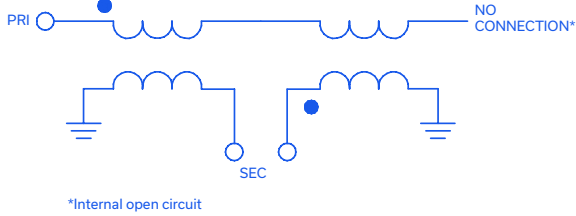
**MAXIMUM RATINGS<sup>3</sup>**

Parameter	Ratings
Operating Temperature	-40°C to 85°C
Input RF Power	33 dBm at 25°C

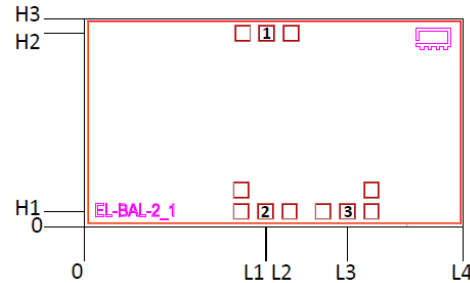
3. Permanent damage may occur if any of these limits are exceeded.



### SIMPLIFIED SCHEMATIC



### BONDING PAD POSITION



### PAD DESCRIPTION

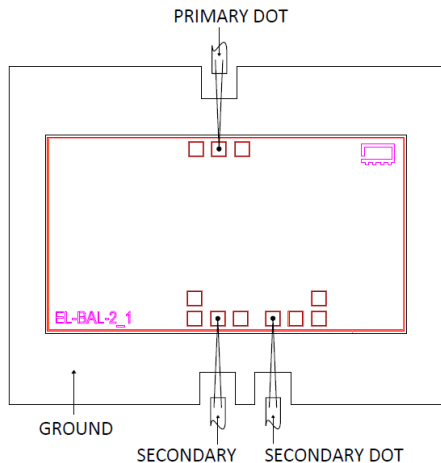
Pad Number	Description
1	Primary Dot
2	Secondary
3	Secondary Dot

### DIE DIMENSIONS IN $\mu\text{m}$


L1	L2	L3	L4	H1	H2	H3
1131	1139	1643	2370	96	1207	1300

Thickness	Die Size	Pad Size 1, 2 & 3
100	2370 x 1300	89 x 89

### ASSEMBLY DIAGRAM



### ASSEMBLY PROCEDURE

- Storage**  
Dice should be stored in a dry nitrogen purged desiccators or equivalent.
-  **ESD**  
MMIC GaAs HBT RF Transformer dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static workstation. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.
- Die Attach**  
The die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are Ablestik 84-1 LMISR4 or equivalents. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufacturer's cure condition. It is recommended to use antistatic die pick up tools only.
- Wire Bonding**  
Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.



**ADDITIONAL DETAILED TECHNICAL INFORMATION IS AVAILABLE ON OUR DASH BOARD.**

<b>Performance Data</b>	Data Table	
	Swept Graphs	
	S-Parameter (S3P Files) Data Set with and without port extension(.zip file)	
<b>Case Style</b>	Die	
<b>Die Ordering and packaging information</b>	Quantity, Package Small, Gel - Pak: 5,10,50,100 KGD* Medium†, Partial wafer: KGD*<672	Model No. MTX2-133-DG+ MTX2-133-DP+
	†Available upon request contact sales representative Refer to AN-60-067	
<b>Environmental Ratings</b>	ENV80	

\*Known Good Dice ("KGD") means that the dice are taken from PCM good wafer and visually inspected. While this is not definitive, it does help to provide a higher degree of confidence that dice are capable of meeting typical RF electrical parameters specified by Mini-Circuits.

**NOTES**

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